



---

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION**

Generic Copy

---

**Issue Date**

**19 Dec 2006**

**SUBJECT: ON Semiconductor Final Product/Process Change Notification #15687**

**TITLE: Additional Assembly/Test Site Qualification for SMB – Site Previously Qualified**

**PROPOSED FIRST SHIP DATE: 19 Feb 2007**

**AFFECTED CHANGE CATEGORY(S): Additional Assembly/Test Site (Previously Qualified)**

**AFFECTED PRODUCT DIVISION(S): Rectifiers**

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <[Jim.Morgan@onsemi.com](mailto:Jim.Morgan@onsemi.com)>

**SAMPLES:**

Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or <[Rick.Leuванos@onsemi.com](mailto:Rick.Leuванos@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**

This notification is an update (includes 3 additional device types) to a previous Final PCN # 11621 issued by ON Semiconductor.

ON Semiconductor has previously qualified LiteOn Seeful (China) to assemble/test SMB Rectifiers. Reliability Qualification has been performed to AEC-Q101 guidelines and all devices have successfully passed testing.

The purpose for updating this PCN is to add these three devices for additional capacity to support demands and reduce product leadtimes.



**Final Product/Process Change Notification #15687**

**RELIABILITY DATA SUMMARY:**

**Reliability Test Results:**

**Test Conditions**

HTRB Vr=80% Max BiasV, Ta=150degC, 1000 hrs.  
 Temp Cycle Air to Air, -65 to +150C, 1000 cycles  
 Autoclave Ta=121C, RH= 100%, PSig=15, 96 hrs.  
 H3TRB Vr=85%V, Ta=85C, RH= 85%, 1000 hrs.  
 IOL Ta=25C, If = 0.8A, 2 minutes on/off, 15000 cycles  
 D.P.A. Post H3TRB and Temp Cycle  
 Physical Dimension Per Case Outline Drawing  
 Res. To Solder Heat 260 C, Td=10s

<b>Test Desc.</b>	<b>Interval</b>	<b>Control</b>	<b>Test Lot A</b>	<b>Test Lot B</b>	<b>Test Lot C</b>
HTRB	1000 hrs	0/80	0/80	0/80	0/80
Temp Cycle	1000 cyc	0/80	0/80	0/80	0/80
Autoclave	96 hrs	0/80	0/80	0/80	0/80
H3TRB	1000 hrs	0/80	0/80	0/80	0/80
IOL	15000 cyc	0/80	0/80	0/80	0/80
D. P. A. -		Pass	Pass	Pass	Pass
Physical Dimension -		Pass	Pass	Pass	Pass
Res. To Solder Heat -		Pass	Pass	Pass	Pass

**ELECTRICAL CHARACTERISTIC SUMMARY:**

No changes to electrical parametrics or specifications

**CHANGED PART IDENTIFICATION:**

Devices marked with Date Code 0703 or newer may be from alternate site.



**Final Product/Process Change Notification #15687**

**AFFECTED DEVICE LIST**

**PART**

MBRS240LT3G  
MBRS2040LT3G  
MBRS1100T3G